

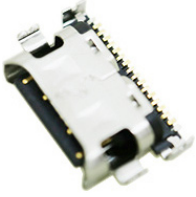
Operation: 沉板式 SMT & U 型舌片



LTEM NO.: MC-311PU-1665 (Consumer Electronics)

(6.55L × 11.00W × 2.96H & T-Flash Sockets)

MEMORY-CARD-SOCKETS



Technical parameter

外焊沉板 SMT

PROJECT	LEVEL	A[better product]	B[average product]
Electrical Properties	Contact Rating	25mA, 24V DC	
	Initial Contact Resistance	30mΩ max.	50mΩ max.
	Insulation Resistance	100MΩ min.500V DC	Key/DP: 100MΩ min.300V DC
Durable Performance	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut
	There No Load	6,500 Cycles	5,500 Cycles
	Rated Load	5,500 Cycles	4,500 Cycles
	Storage temp.	-25℃~+85℃(Operating Temp: )	

側向導入 LATERAL

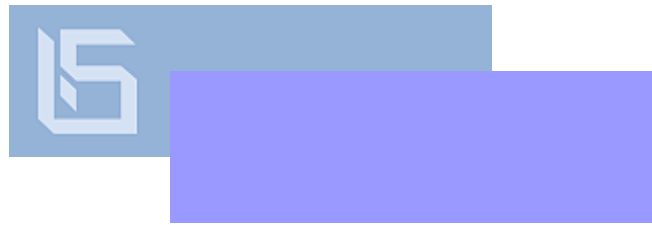
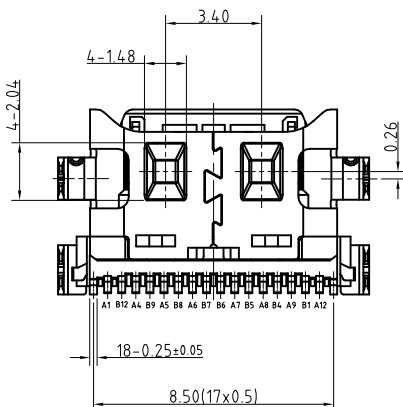
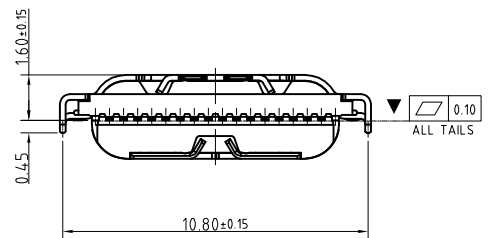
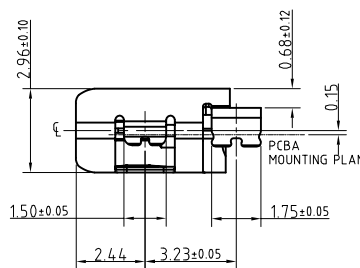
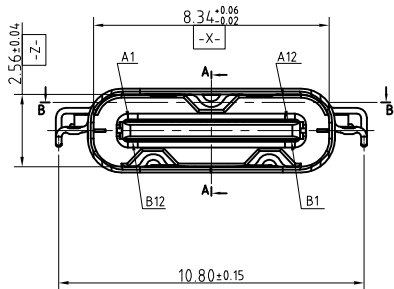
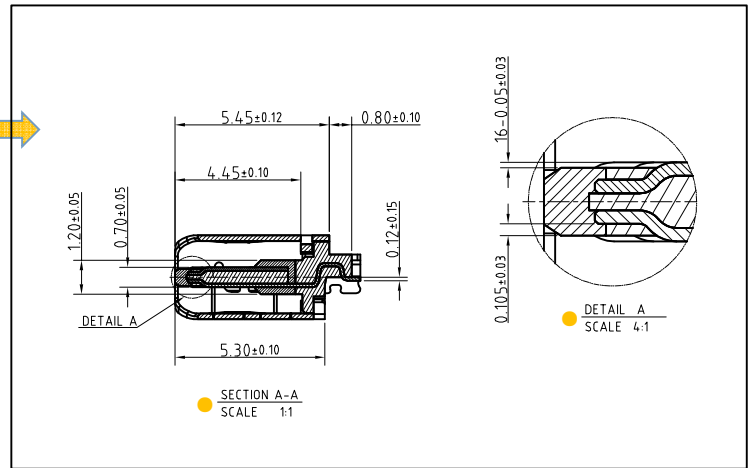
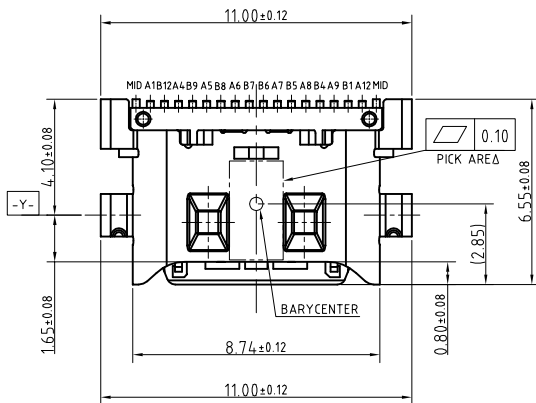
精密部品 NICETY

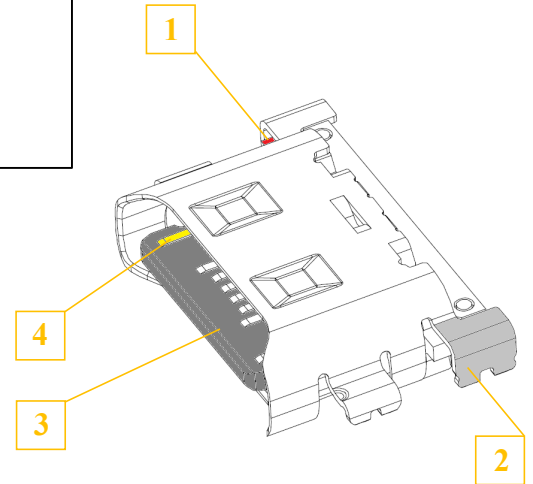
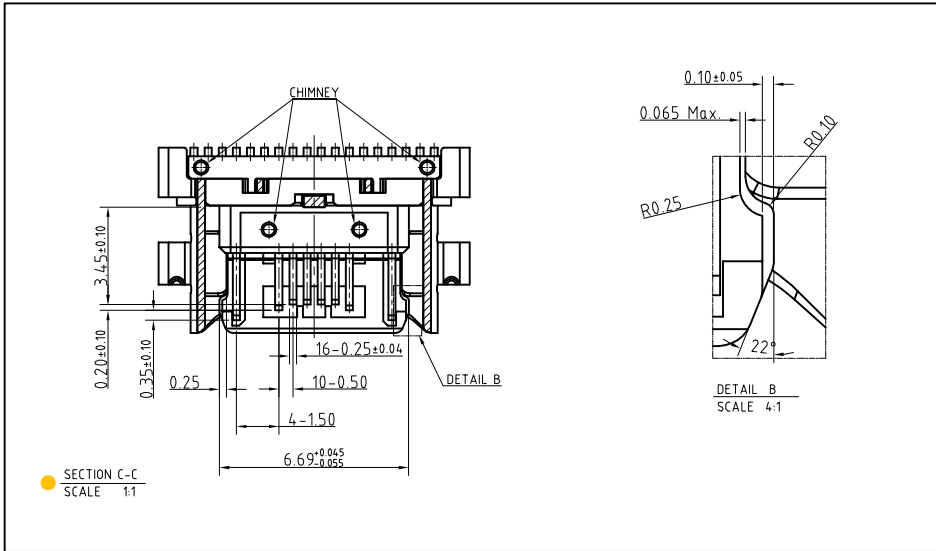
可靠 STABILIZE

適合環保 RoHS

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Unit:mm





# SPECIFIED TOLERANCES

UNLESS OTHERWISE



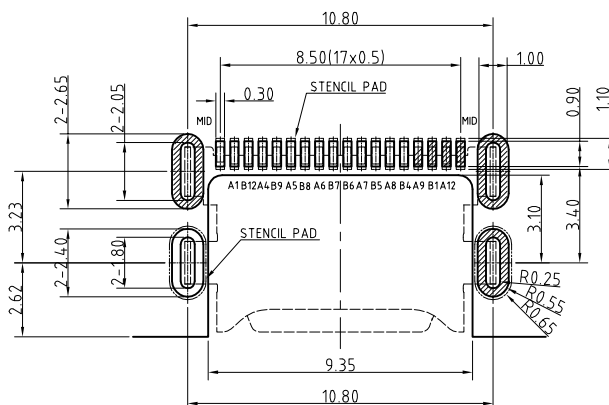
DECIMALS	ANGLES
X.X : ±0.35	X.X : ±3°
X.XX : ±0.25	X.XX : ±2°
X.XXX : ±0.15	

Material declaration			
No.	NAME	MATERIAL	DESCRIPTION
① A	TERMINAL	COPPER ALLOY 【G/F】	2.0 μm Ni PLATED OVERALL; 0.25 μm Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
② B	SHIELDING PLATE	STAINLESS 【G/F】	0.25 μm Ni PLATED OVERALL;
③ C	HOUSING	THERMOPLASTIC	UL 94V-0,COLOR:BLACK;
④ D	SHELL	STAINLESS 【G/F】	0.25 μm Ni PLATED OVERALL;



# MATERIAL

Operating Force	Inward	8.0~20.0N. (1N.=100gram-force)
	Exiting	6.0~20.0N. (1N.=100gram-force)MIN



RECOMMENDED PCB LAYOUT  
TOLERANCE ±0.05

Pin definition



PIN	Signal NAME	PIN	Signal NAME
A 1	GND	B12	GND
A 4	V BUS	B 9	V BUS
A 5	CC1	B 8	SBU2
A 6	Dp1	B 7	Dn2
A 7	Dn1	B 6	Dp2
A 8	SBU1	B 5	CC2
A 9	V BUS	B 4	V BUS
A12	GND	B 1	GND

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